



PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of :
DiStefano, et al. : Group Art Unit: 2812
:
U.S. Application No. 09/638,079 :
: Examiner:
Filed: August 14, 2000 :
:
For: METHODS FOR PROVIDING : Date: November 28, 2000
VOID-FREE LAYERS FOR :
SEMICONDUCTOR ASSEMBLIES :
X

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Preliminary to initiation of the prosecution of the
above-identified U.S. patent application, the following
amendments and remarks are respectfully submitted.

IN THE ABSTRACT

Please delete the Abstract originally filed with
this application, and substitute therefor the enclosed revised
Abstract.

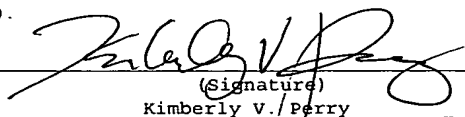
IN THE CLAIMS

Please cancel claim 1 and substitute therefor the
following new claims:

al
contd

1/. A method of providing a substantially void free
underfill for a flip chip assembly, comprising:

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Kimberly V. Perry

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